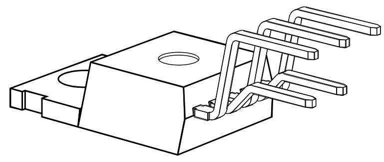
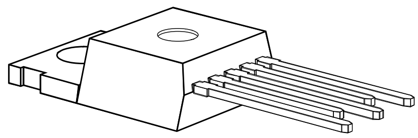
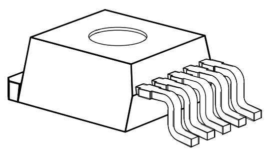
5-V Low-Drop Fixed Voltage Regulator **TLE 4270**

Features

- Output voltage tolerance ≤ ± 2 %
- 650 mA output current capability
- Low-drop voltage
- Reset functionality
- Adjustable reset time
- Suitable for use in automotive electronics
- Integrated overtemperature protection
- Reverse polarity protection
- Input voltage up to 42 V
- Overvoltage protection up to 65 V (≤ 400 ms)
- Short-circuit proof
- Wide temperature range
- ESD protection > 4000 V


P-TO220-5-11


P-TO220-5-12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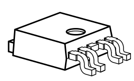

P-TO252-5-1

Type	Ordering Code	Package
TLE 4270	Q67000-A9209	P-TO220-5-11
TLE 4270 S	Q67000-A9243	P-TO220-5-12
TLE 4270 G	Q67006-A9201	P-TO263-5-1
TLE 4270 D	Q67006-A9360	P-TO252-5-1

Functional Description

This device is a 5-V low-drop fixed-voltage regulator. The maximum input voltage is 42 V (65 V, ≤ 400 ms). Up to an input voltage of 26 V and for an output current up to 650 mA it regulates the output voltage within a 2 % accuracy. The short circuit protection limits the output current of more than 650 mA. The device incorporates overvoltage protection and a temperature protection which turns off the device at high temperatures.

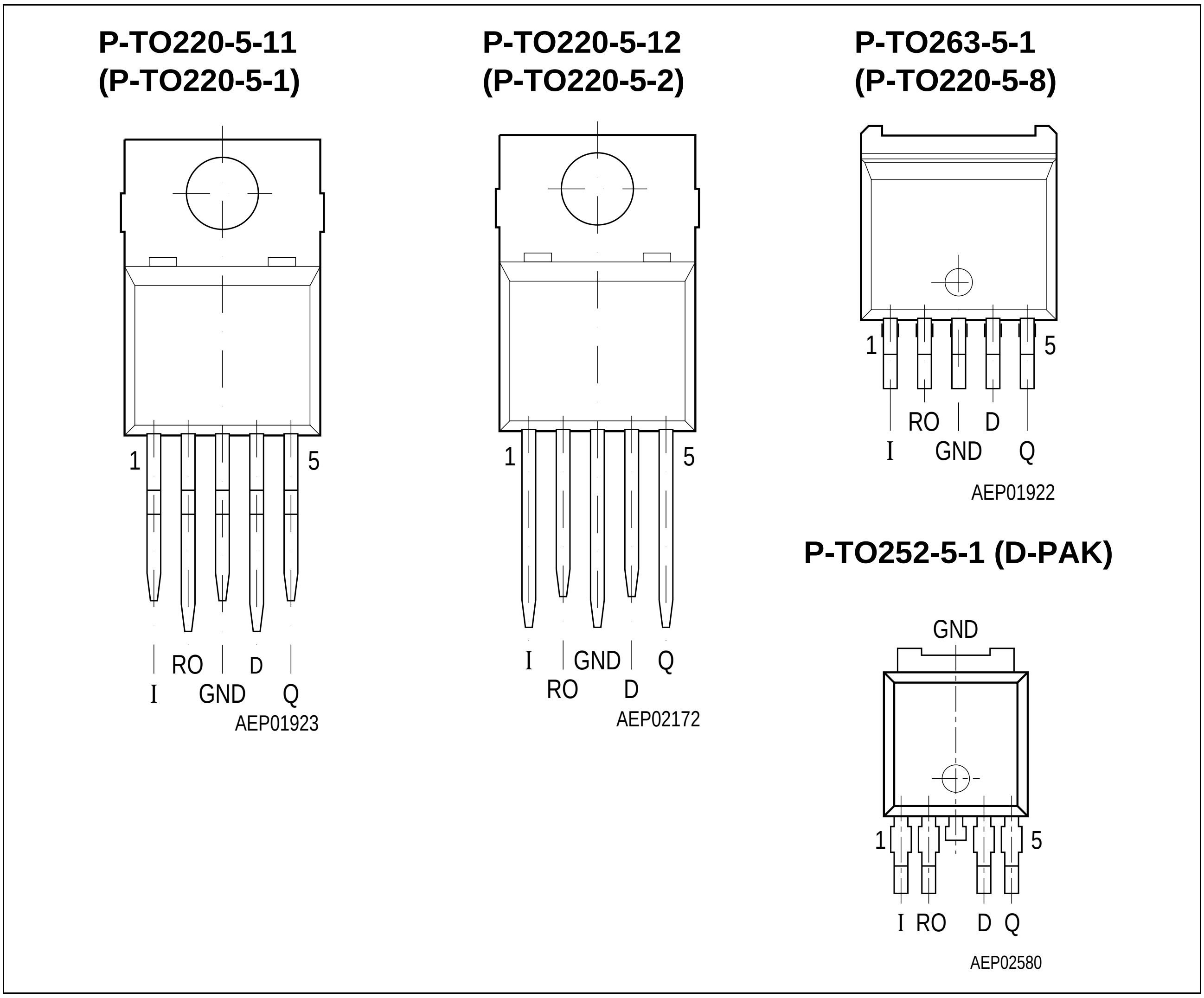


Figure 1 **Pin Configuration** (top view)

Pin Definitions and Functions

Pin	Symbol	Function
1	I	**Input**; block to ground directly at the IC with a ceramic capacitor
2	RO	**Reset Output**; the open collector output is connected to the 5 V output via an integrated resistor of 30 kΩ.
3	GND	**Ground**; internally connected to heatsink.
4	D	**Reset Delay**; connect a capacitor to ground for delay time adjustment.
5	Q	**5-V Output**; block to ground with 22 μF capacitor, ESR $<$ 3 Ω.

Circuit Description

The control amplifier compares a reference voltage, which is kept highly accurate by resistance adjustment, to a voltage that is proportional to the output voltage and drives the base of a series transistor via a buffer. Saturation control as a function of the load current prevents any over-saturation of the power element.

The IC also incorporates a number of internal circuits for protection against:

- Overload
- Overvoltage
- Overtemperature
- Reverse polarity

Application Description

The IC regulates an input voltage in the range of 5.5 V $< V_{\mathrm{I}} <$ 36 V to $V_{\mathrm{Q,nom}}$ = 5.0 V. Up to 26 V it produces a regulated output current of more than 650 mA. Above 26 V the save-operating-area protection allows operation up to 36 V with a regulated output current of more than 300 mA. Overvoltage protection limits operation at 42 V. The overvoltage protection hysteresis restores operation if the input voltage has dropped below 36 V. A reset signal is generated for an output voltage of $V_{\mathrm{Q}} <$ 4.5 V. The delay for power-on reset can be set externally with a capacitor.

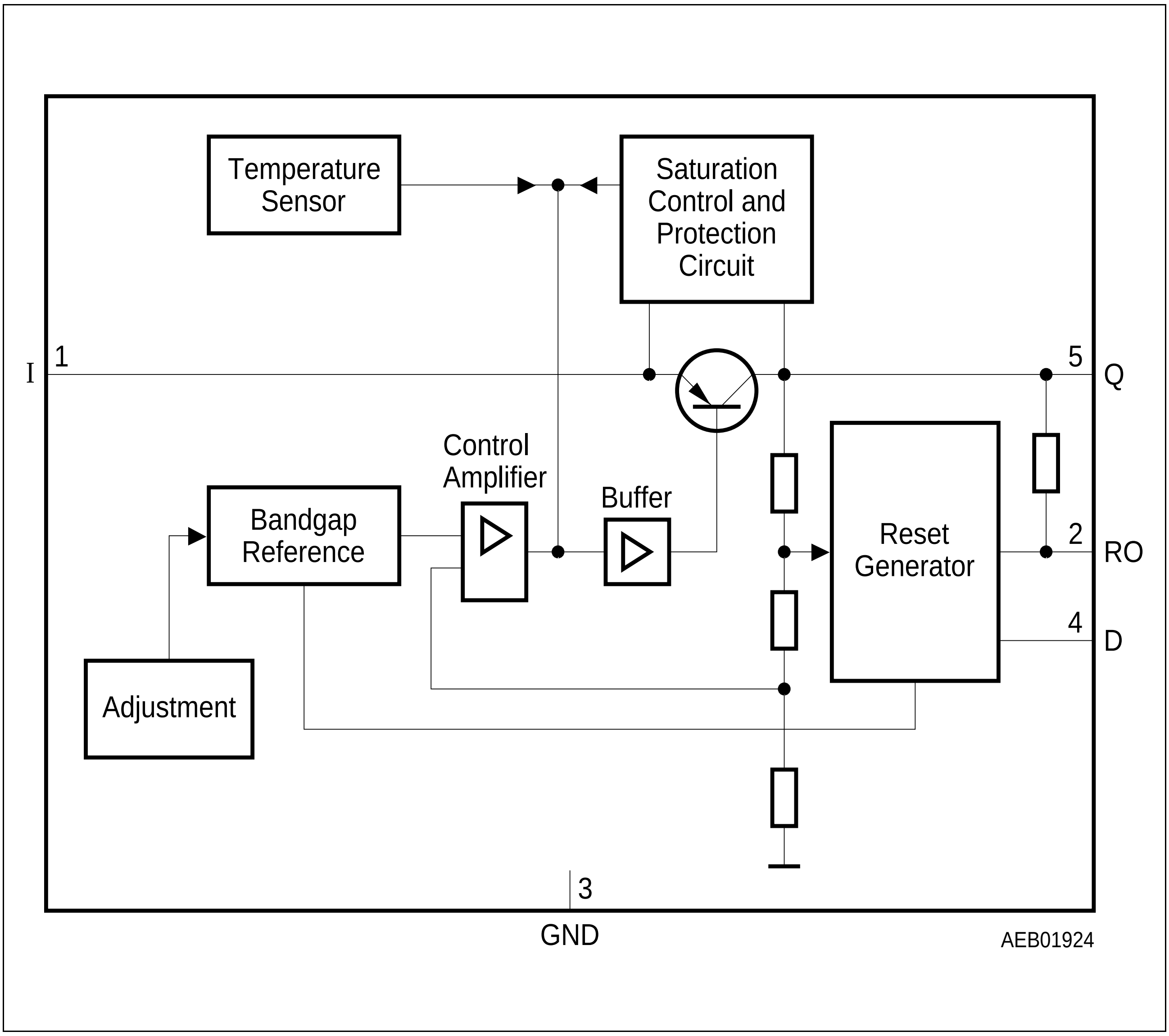


Figure 2 **Block Diagram**

Absolute Maximum Ratings

T_j = – 40 to 150 °C

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Input I					
Voltage	V_I	– 42	42	V	
Voltage	V_I	–	65	V	$t \leq$ 400 ms
Current	I_I	–	–	–	internally limited
Reset Output RO					
Voltage	V_{RO}	– 0.3	7	V	
Current	I_{RO}	–	–	–	Internally limited
Reset Delay D					
Voltage	V_D	– 0.3	7	V	
Current	I_D	–	–	–	Internally limited
Output Q					
Voltage	V_Q	– 1.0	16	V	
Current	I_Q	–	–	–	Internally limited
Ground GND					
Current	I_{GND}	– 0.5	–	A	–
Temperatures					
Junction temperature	T_j		150	°C	–
Storage temperature	T_{stg}	– 50	150	°C	

Operating Range

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Input voltage	V_I	6	42	V	–
Junction temperature	T_j	– 40	150	°C	–

Thermal Resistance

Junction ambient	R_{thj-a}	–	65 79	K/W K/W	 TO263, TO252[1)]
Junction case	R_{thj-c}	–	3	K/W	TO-220/263 Packages

1) Mounted on PCB, 80 × 80 × 1.5 mm[3]; 35µ Cu; 5µ Sn; Footprint only; zero airflow.

Characteristics

V_I = 13.5 V; – 40 °C ≤ T_j = ≤ 125 °C (unless otherwise specified)

Parameter	Symbol	Limit Values			Unit	Test Condition
		min.	typ.	max.		
Output voltage	V_Q	4.90	5.00	5.10	V	5 mA ≤ I_Q ≤ 550 mA; 6 V ≤ V_I ≤ 26 V
Output voltage	V_Q	4.90	5.00	5.10	V	26 V ≤ V_I ≤ 36 V; I_Q ≤ 300 mA
Output current limiting	I_{Qmax}	650	850	–	mA	V_Q = 0 V
Current consumption $I_q = I_I - I_Q$	I_q	–	1	1.5	mA	I_Q = 5 mA
Current consumption $I_q = I_I - I_Q$	I_q	–	55	75	mA	I_Q = 550 mA
Current consumption $I_q = I_I - I_Q$	I_q	–	70	90	mA	I_Q = 550 mA; V_I = 5 V
Drop voltage	V_{DR}	–	350	700	mV	I_Q = 550 mA[1)]

Characteristics (cont'd)
V_I = 13.5 V; – 40 °C ≤ T_j = ≤ 125 °C (unless otherwise specified)

Parameter	Symbol	Limit Values			Unit	Test Condition
		min.	typ.	max.		
Load regulation	$\Delta V_{Q,Lo}$	–	25	50	mV	I_Q = 5 to 550 mA; V_I = 6 V
Line regulation	$\Delta V_{Q,Li}$	–	12	25	mV	V_I = 6 to 26 V I_Q = 5 mA
Power supply Ripple rejection	$PSRR$	–	54	–	dB	f_r = 100 Hz; V_r = 0.5 V_{SS}

Reset Generator

Switching threshold	V_{RT}	4.5	4.65	4.8	V	–
Reset High voltage	V_{ROH}	4.5	–	–	V	–
Reset low voltage	V_{ROL}	–	60	–	mV	R_{int} = 30 kΩ[2]; 1.0 V ≤ V_Q ≤ 4.5 V
Reset low voltage	V_{ROL}	–	200	400	mV	I_R = 3 mA, V_Q = 4.4 V
Reset pull-up	R_{int}	18	30	46	kΩ	internally connected to Q
Charge current	$I_{D,c}$	8	14	25	µA	V_D = 1.0 V
Upper reset timing threshold	V_{DU}	1.4	1.8	2.3	V	–
Lower reset timing threshold	V_{DL}	0.2	0.45	0.8	V	$V_Q < V_{RT}$
Delay time	t_{rd}	–	13	–	ms	C_D = 100 nF
Reset reaction time	t_{rr}	–	–	3	µs	C_D = 100 nF

Overvoltage Protection

Turn-Off voltage	$V_{I,\,ov}$	42	44	46	V	–

1) Drop voltage = $V_I - V_Q$ (measured when the output voltage has dropped 100 mV from the nominal value obtained at 13.5 V input)
2) Reset peak is always lower than 1.0 V.

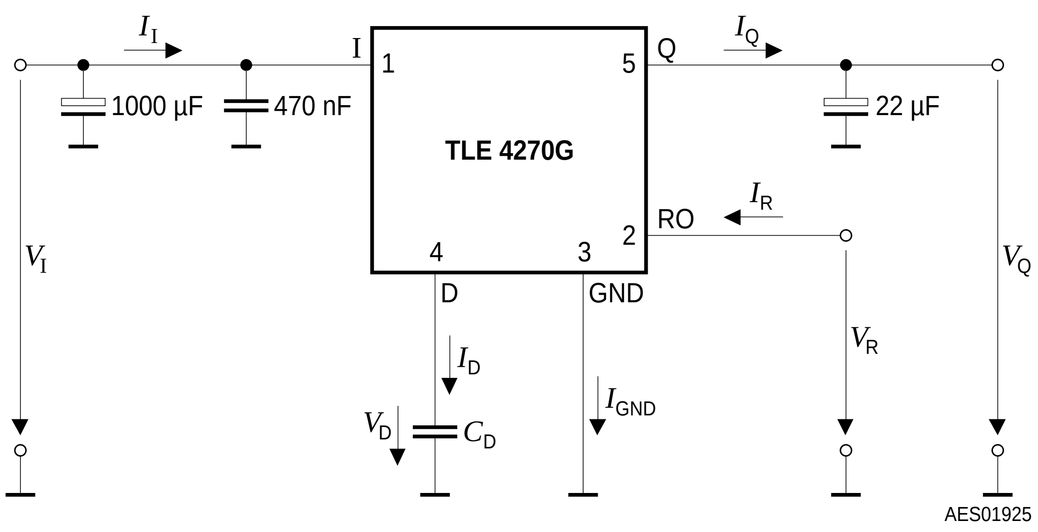


Figure 3 Test Circuit

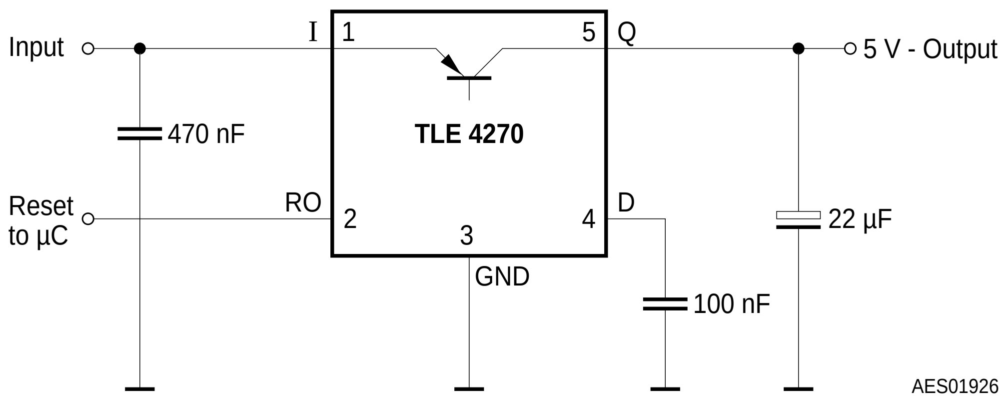


Figure 4 Application Circuit

Design Notes for External Components

An input capacitor C_I is necessary for compensation of line influences. The resonant circuit consisting of lead inductance and input capacitance can be damped by a resistor of approx. 1 Ω in series with C_I. An output capacitor C_Q is necessary for the stability of the regulating circuit. Stability is guaranteed at values of $C_Q \geq 22$ µF and an ESR of < 3 Ω.

Reset Circuitry

If the output voltage decreases below 4.5 V, an external capacitor C_D on pin 4 (D) will be discharged by the reset generator. If the voltage on this capacitor drops below V_{DL}, a reset signal is generated on pin 2 (RO), i.e. reset output is set low. If the output voltage rises above the reset threshold, C_D will be charged with constant current. After the power-on-reset time the voltage on the capacitor reaches V_{DU} and the reset output will be set high again. The value of the power-on-reset time can be set within a wide range depending of the capacitance of C_D.

Reset Timing

The power-on reset delay time is defined by the charging time of an external capacitor C_D which can be calculated as follows:

$$C_D = (\Delta t \times I_{D,c})/\Delta V$$

Definitions: C_D = delay capacitors

Δt = reset delay time t_{rd}

$I_{D,c}$ = charge current, typical 14 µA

$\Delta V = V_{DU}$, typical 1.8 V

V_{DU} = upper reset timing threshold at C_D for reset delay time

$t_{rd} = \Delta V \times C_D / I_{D,c}$

The reset reaction time t_{rr} is the time it takes the voltage regulator to set the reset out LOW after the output voltage has dropped below the reset threshold. It is typically 1 µs for delay capacitor of 47 nF. For other values for C_D the reaction time can be estimated using the following equation:

$$t_{rr} \approx 20 \text{ s/F} \times C_D$$

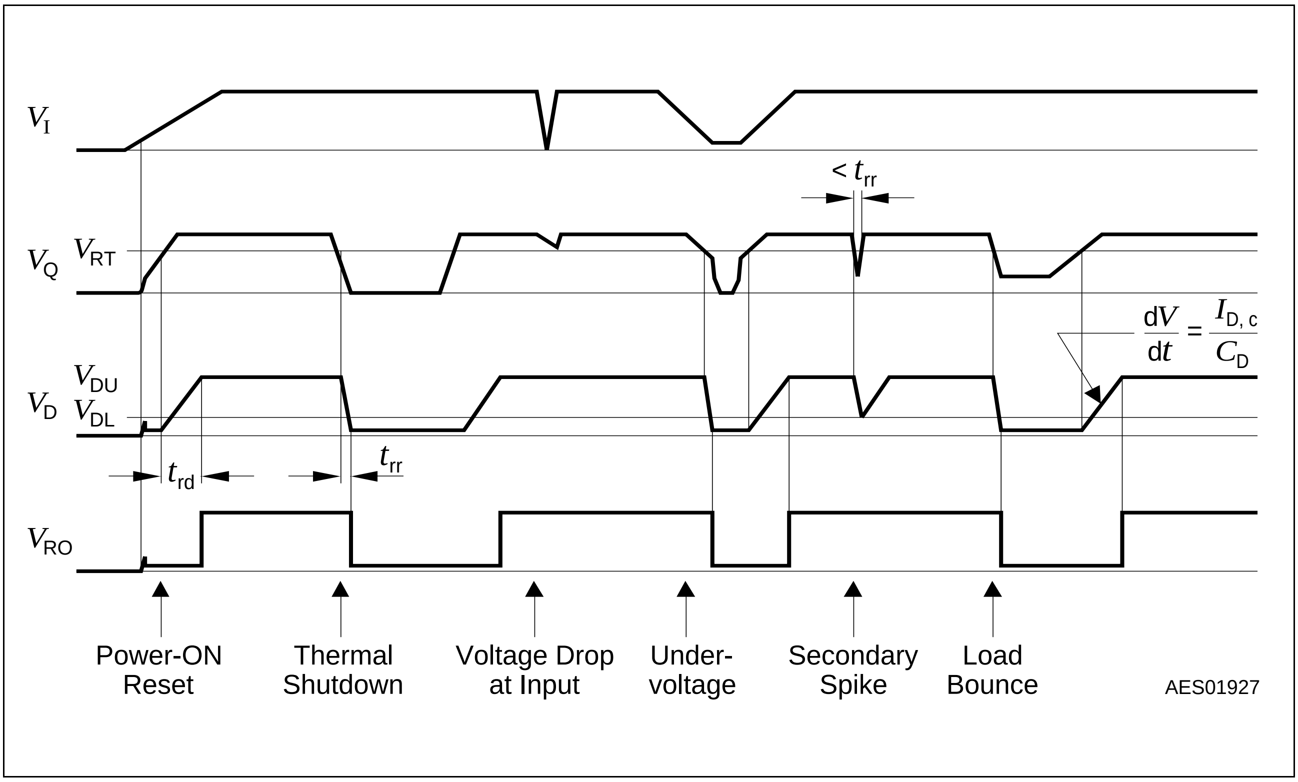
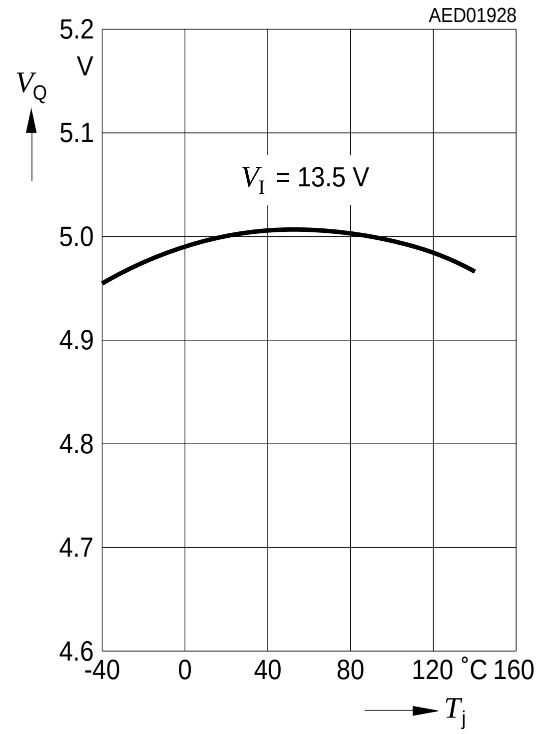
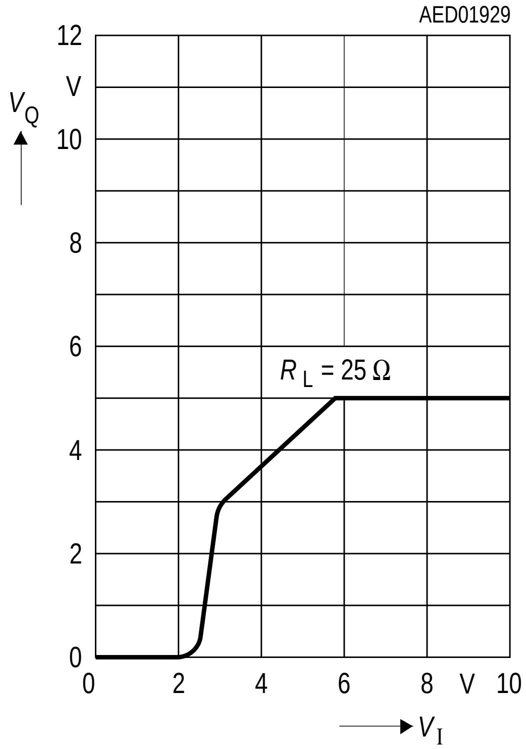


Figure 5 Reset Time Response

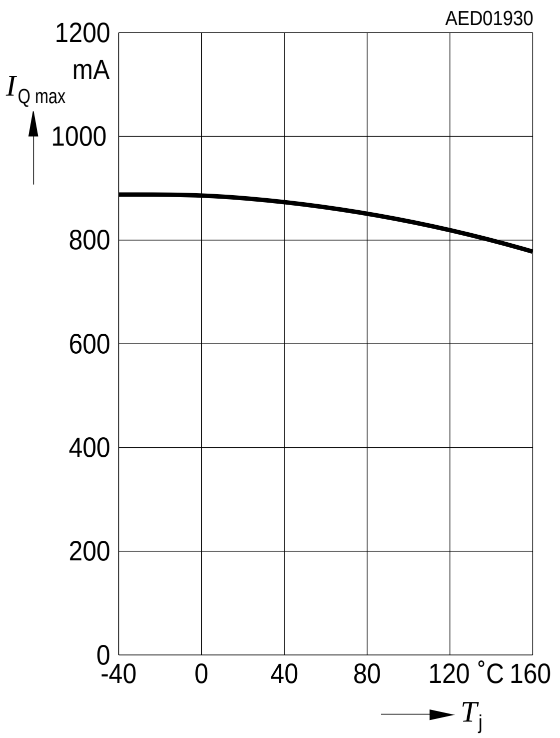
Output Voltage V_Q versus Temperature T_j



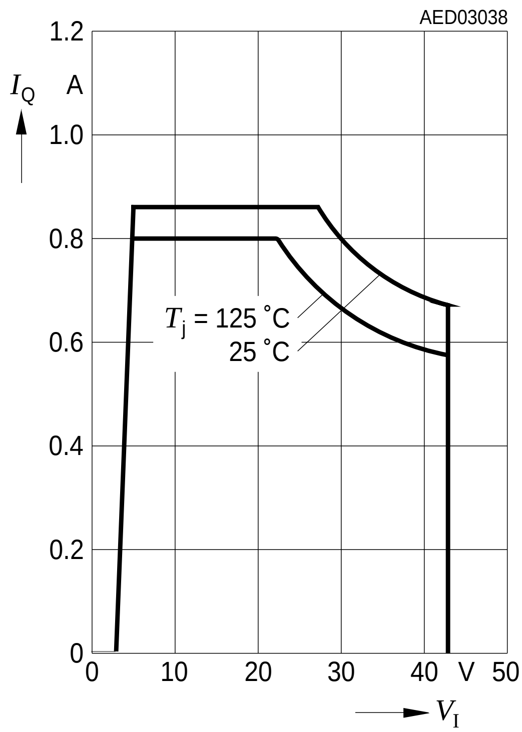
Output Voltage V_Q versus Input Voltage V_I



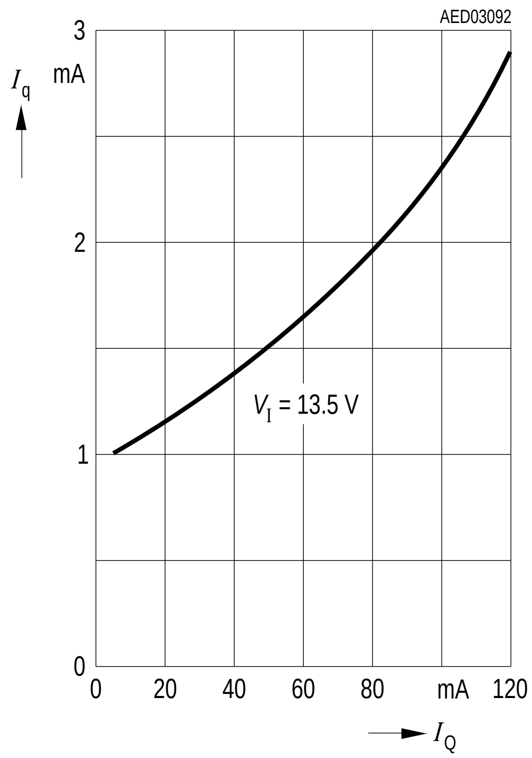
Output Current I_Q versus Temperature T_j



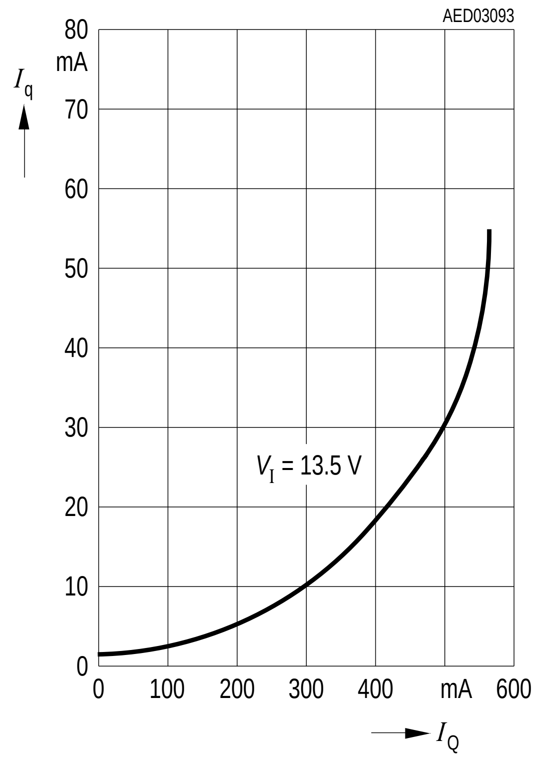
Output Current I_Q versus Input Voltage V_I



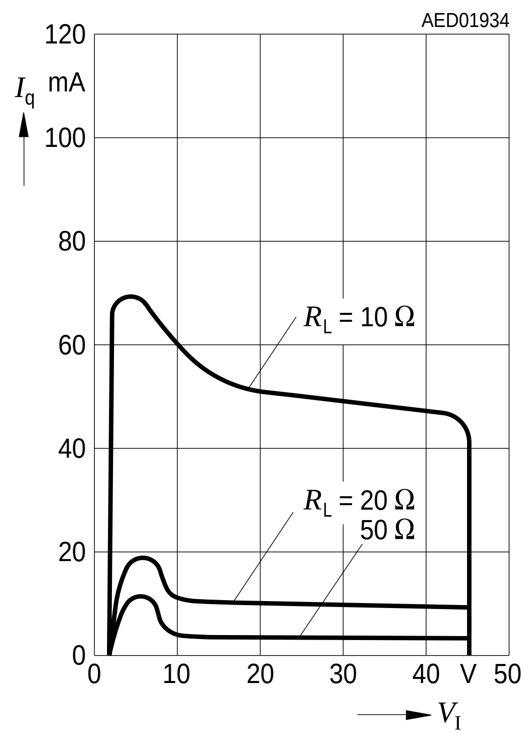
Current Consumption I_q versus Output Current I_Q



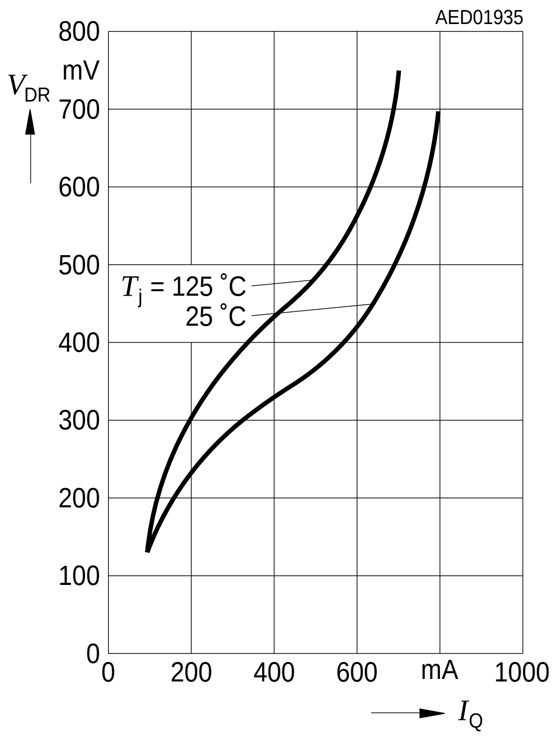
Current Consumption I_q versus Output Current I_Q



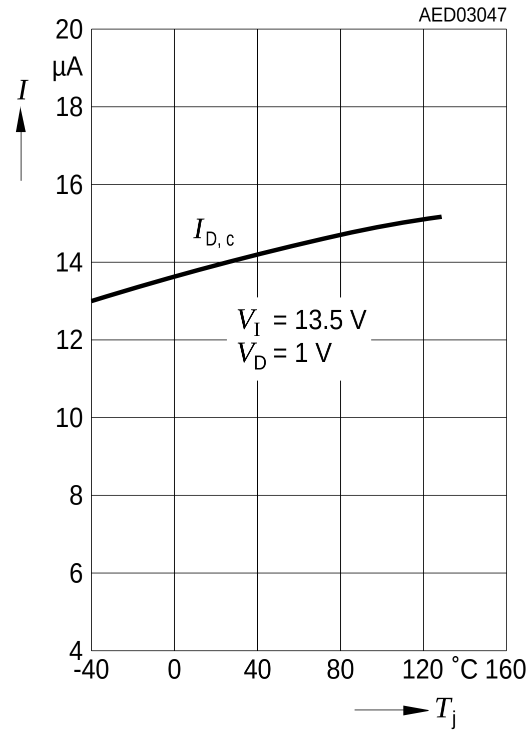
Current Consumption I_q versus Input Voltage V_I



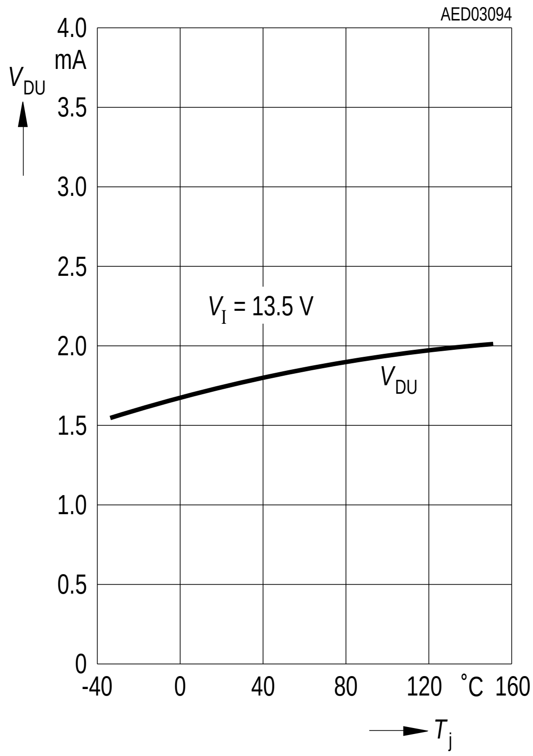
Drop Voltage V_{DR} versus Output Current I_Q



Charge Current $I_{D,c}$ versus Temperature T_j

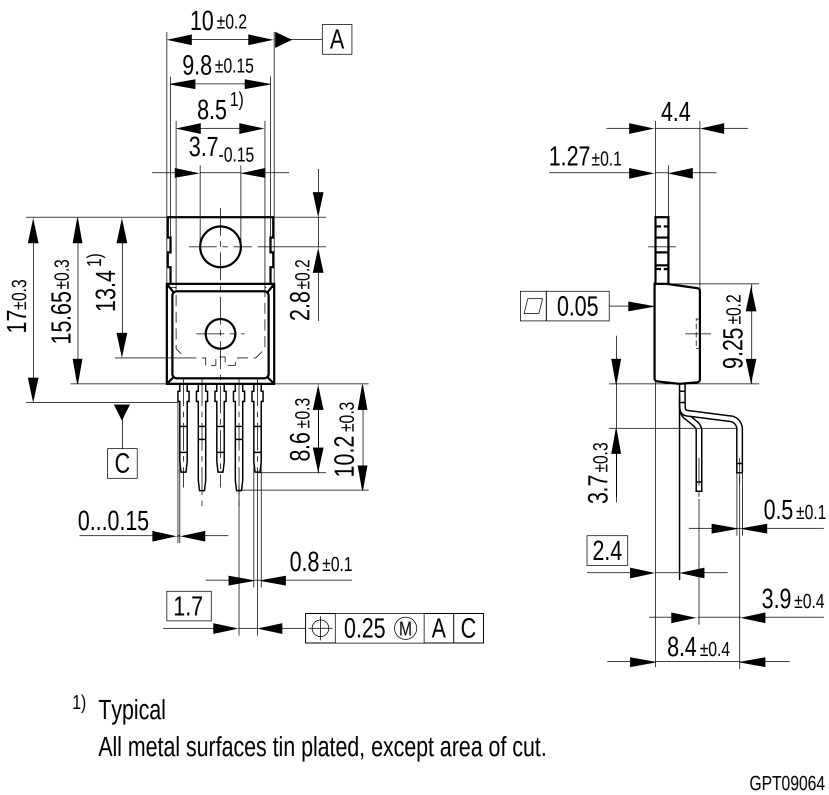


Upper Reset Timing Threshold V_{DU} versus Temperature T_j



Package Outlines

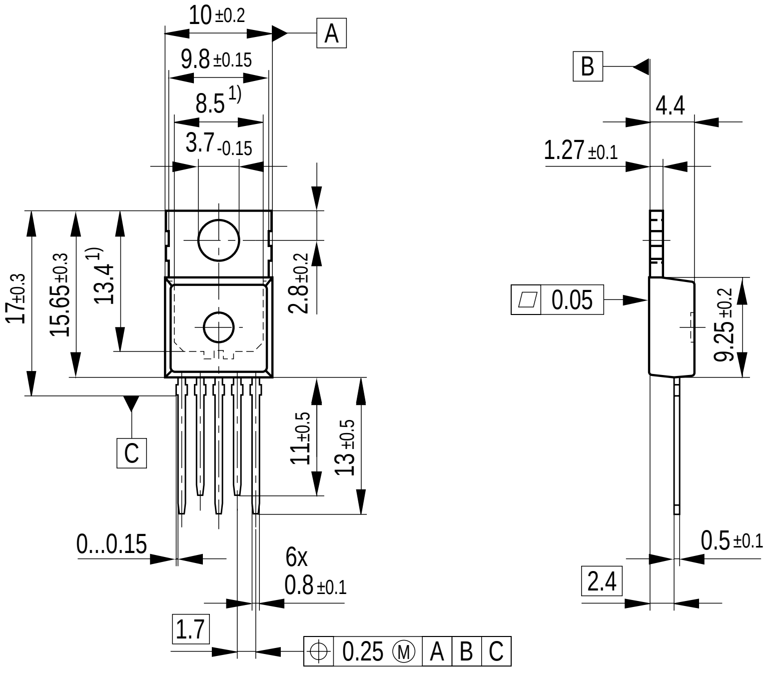
P-TO220-5-11
(Plastic Transistor Single Outline)



Sorts of Packing
Package outlines for tubes, trays etc. are contained in our Data Book “Package Information”.

Dimensions in mm

P-TO220-5-12
(Plastic Transistor Single Outline)



Typical
1) All metal surfaces tin plated, except area of cut.

GPT09065

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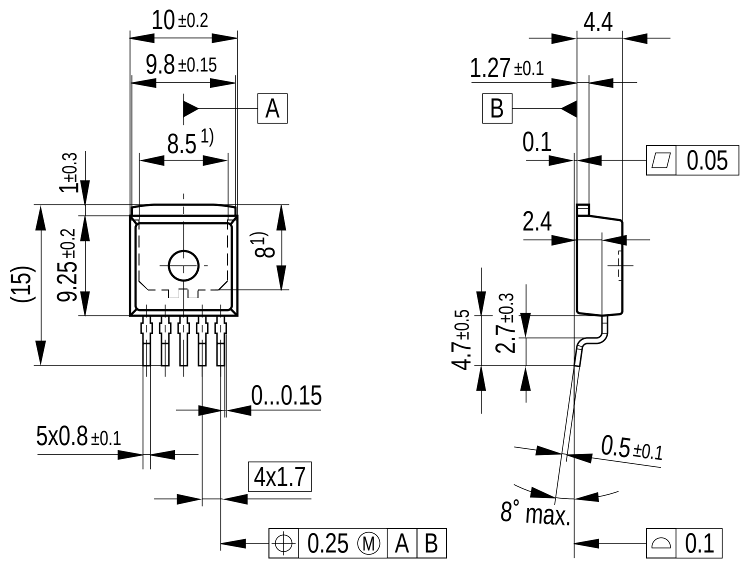
Dimensions in mm

P-TO263-5-1
(Plastic Transistor Single Outline)



1) Typical
All metal surfaces tin plated, except area of cut.

GPT09113

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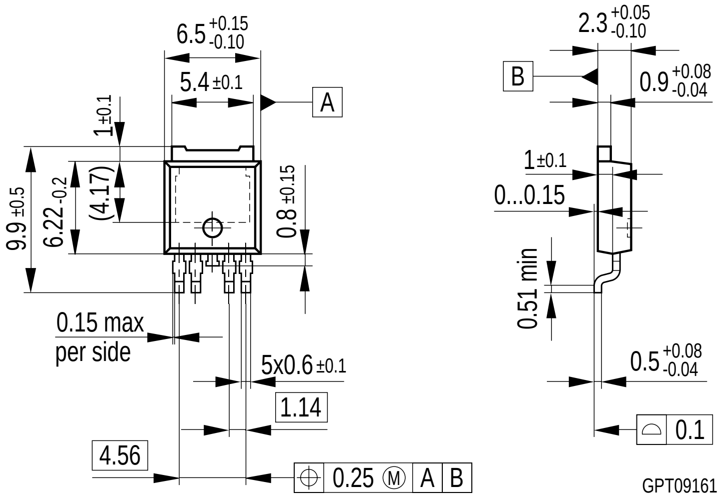
SMD = Surface Mounted Device

Dimensions in mm

P-TO252-5-1
(Plastic Transistor Single Outline)



All metal surfaces tin plated, except area of cut.

GPT09161

Sorts of Packing
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SMD = Surface Mounted Device

Dimensions in mm

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